



Dear Valued Customer,

The current mechanical specifications for the package can be found at the www.national.com web site or by clicking the following link:

<http://www.national.com/packaging/folders/sda08a.html>

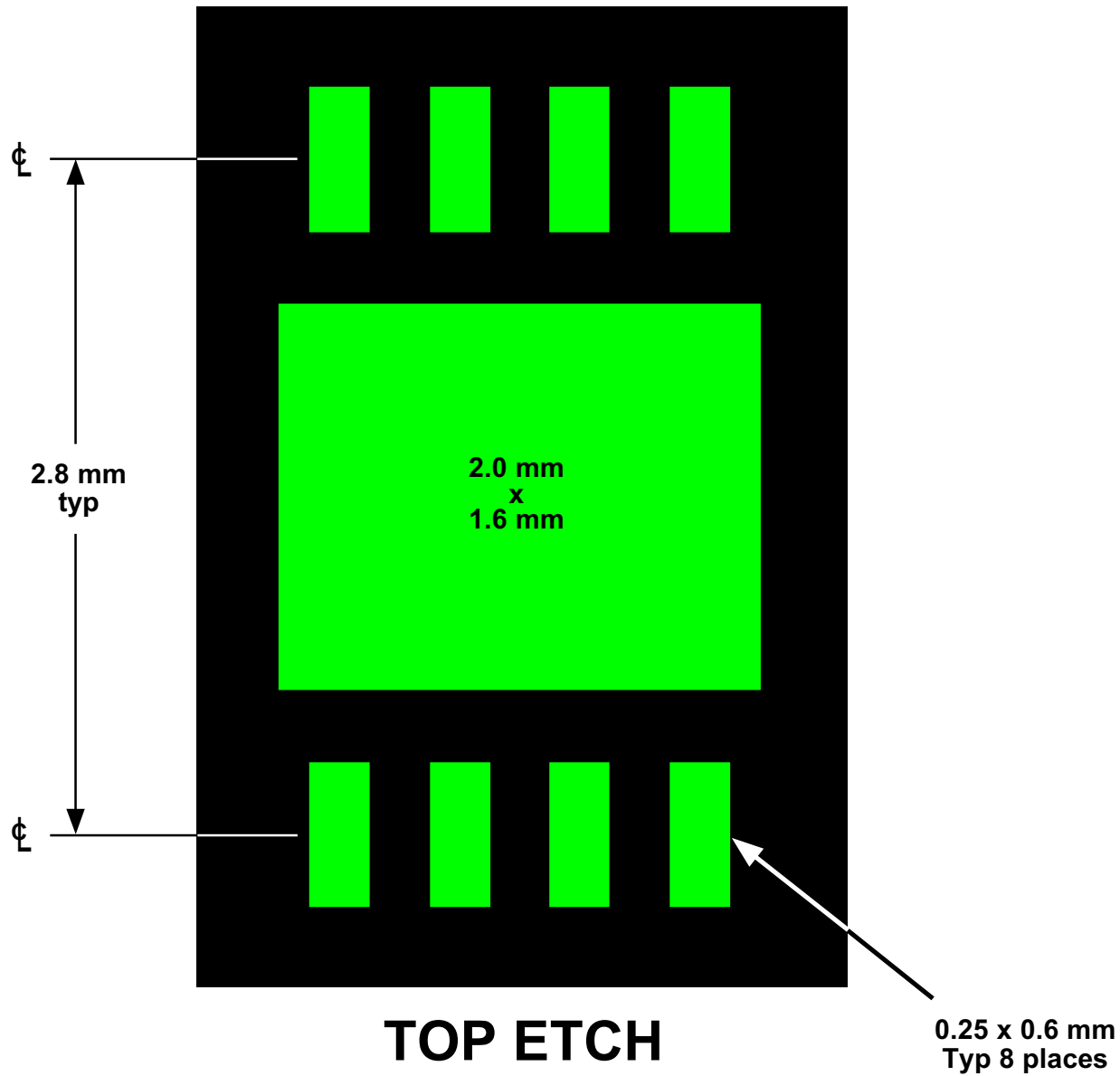
The following pages illustrate the recommended package footprints that apply to this package configuration. They are included in GERBER format for easy incorporation into most PCB layout packages.

For technical support, contact:

<http://www.national.com/support/>

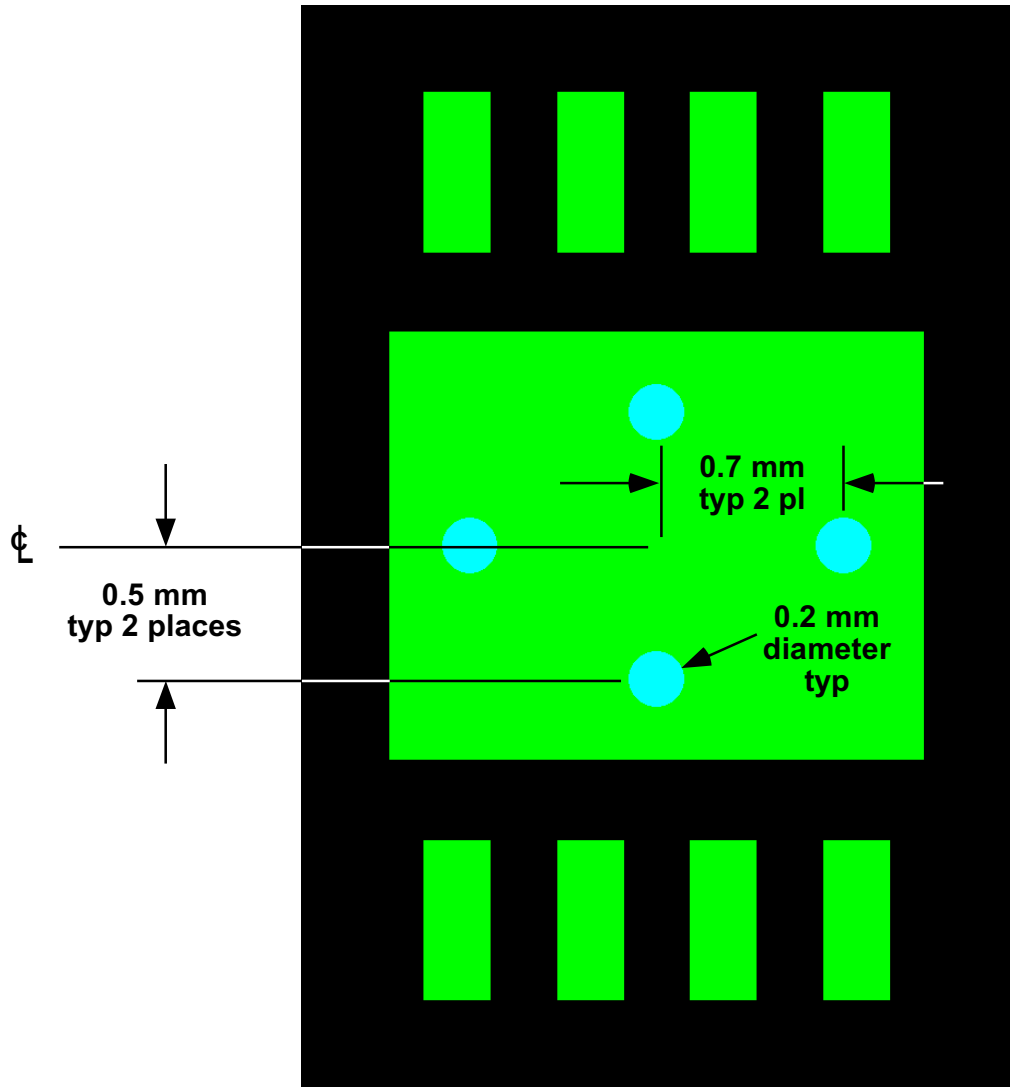
Sincerely yours,

National Semiconductor




 = Exposed FR4  = Exposed metal


NOTE:
Refer to package mechanical
drawing at the website for complete
mechanical dimensions.

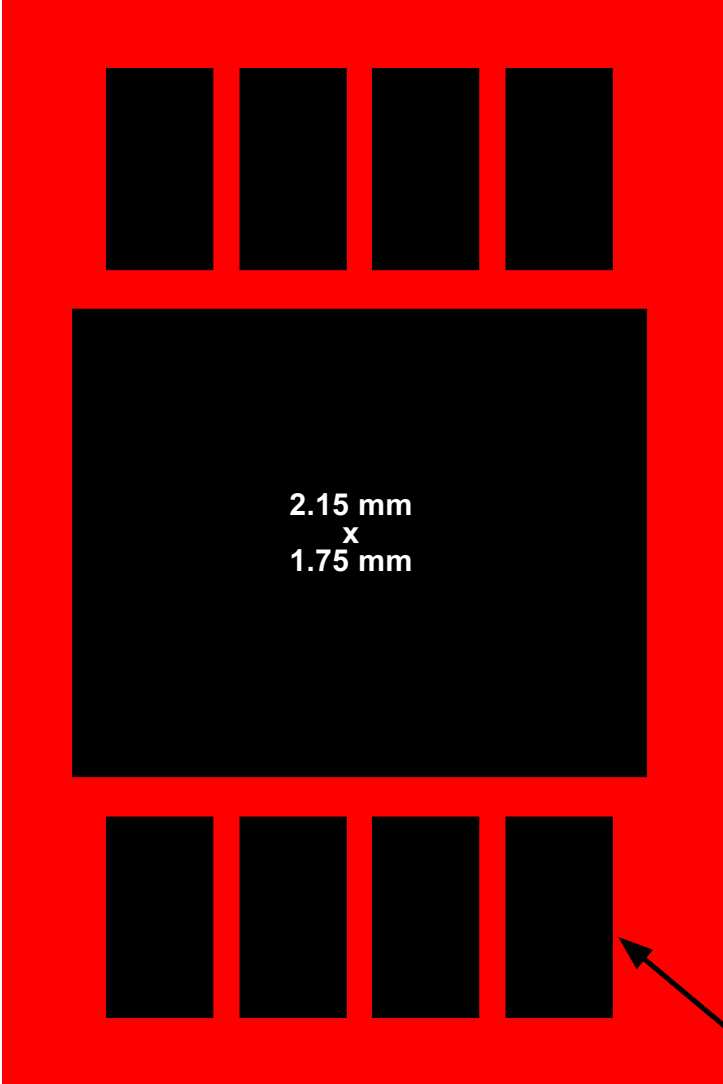


TOP ETCH with THERMAL VIAS

 = Exposed FR4


 = Exposed metal

 = Thermal Vias



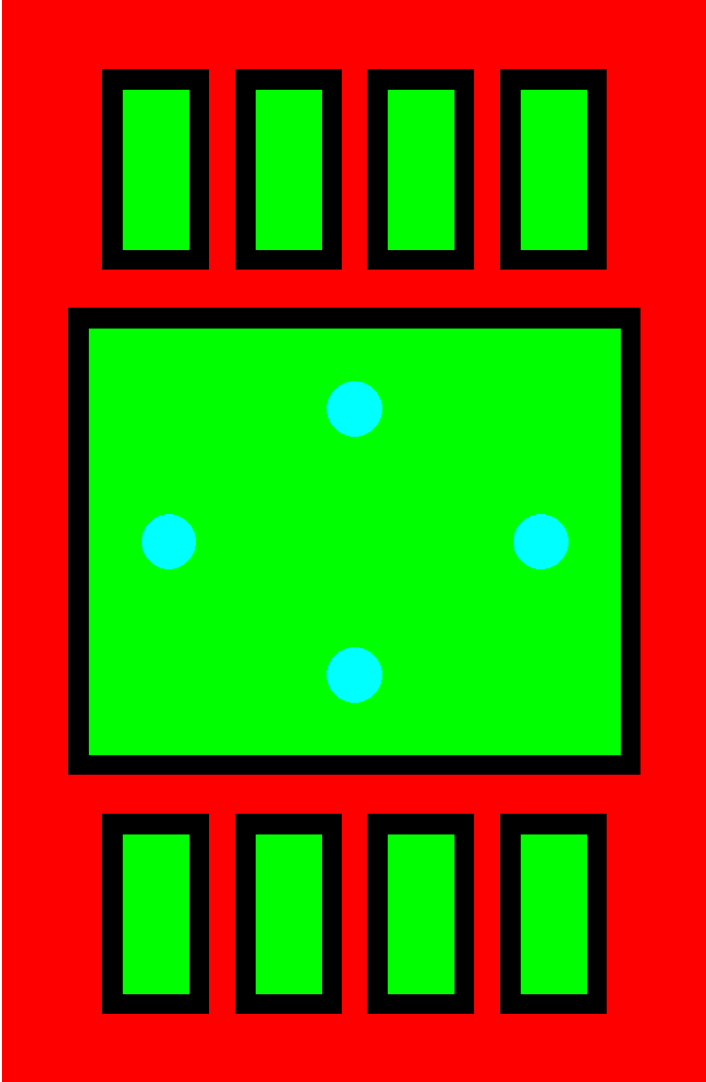
2.15 mm
x
1.75 mm

0.4 x 0.75 mm
Typ 8 places

 = Exposed FR4

 = Mask over FR4

TOP SOLDERMASK



TOP ETCH + SOLDERMASK + VIAS



= Exposed FR4



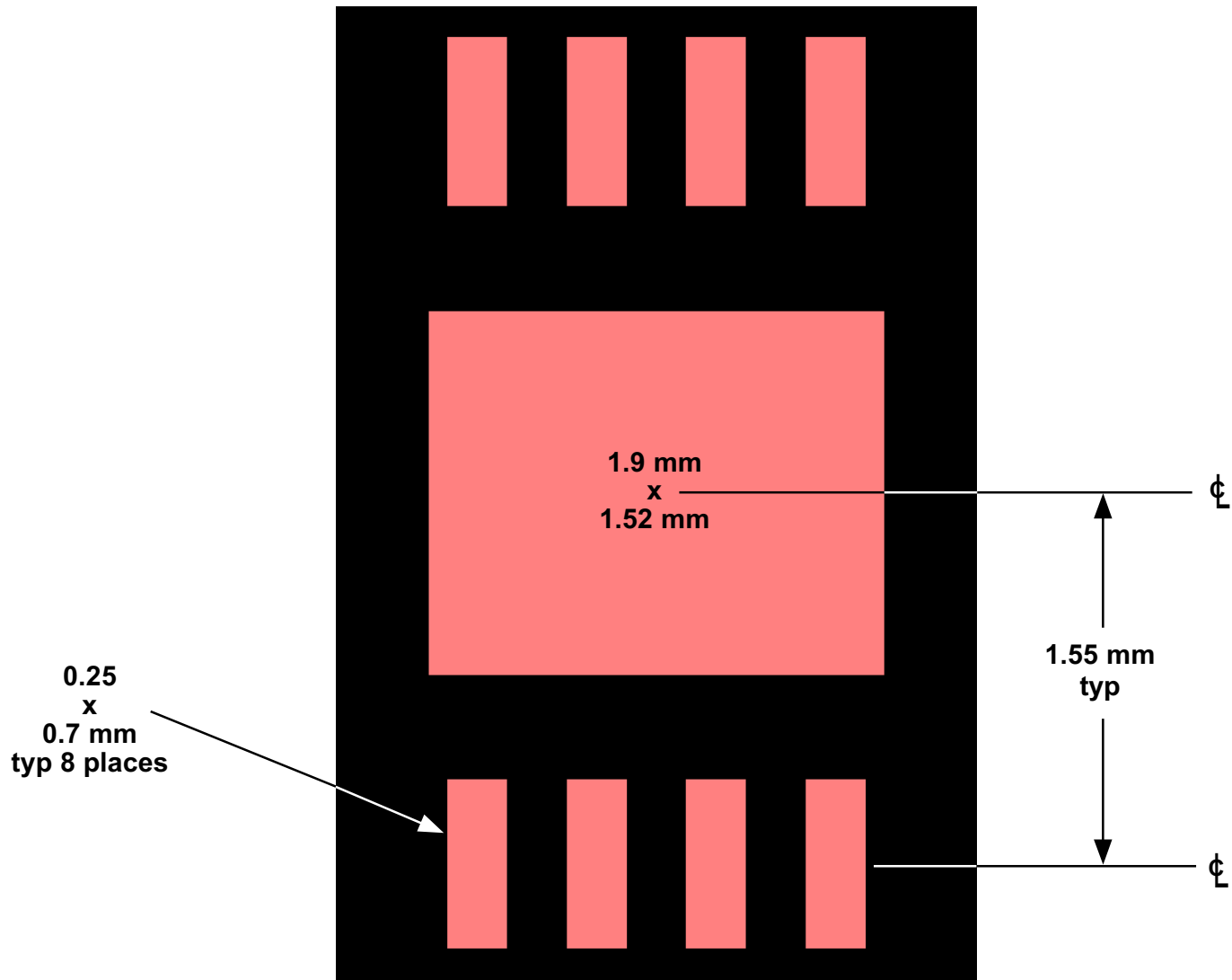
= Exposed metal



= Thermal Vias



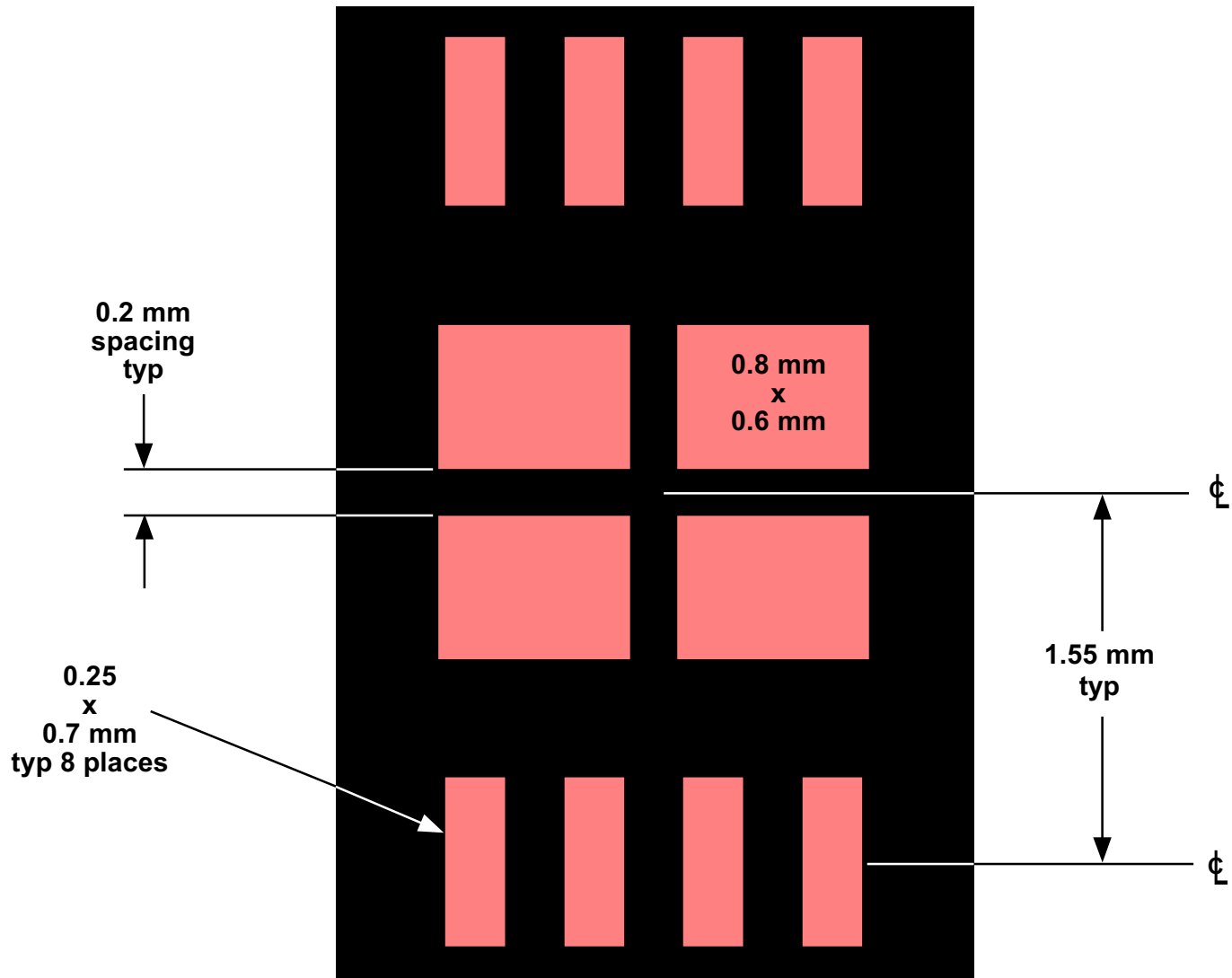
= Mask over FR4



TOP SOLDERPASTE for High Power Devices or PCBs with Top Metal Ground Planes (Opt 1)

 = Paste

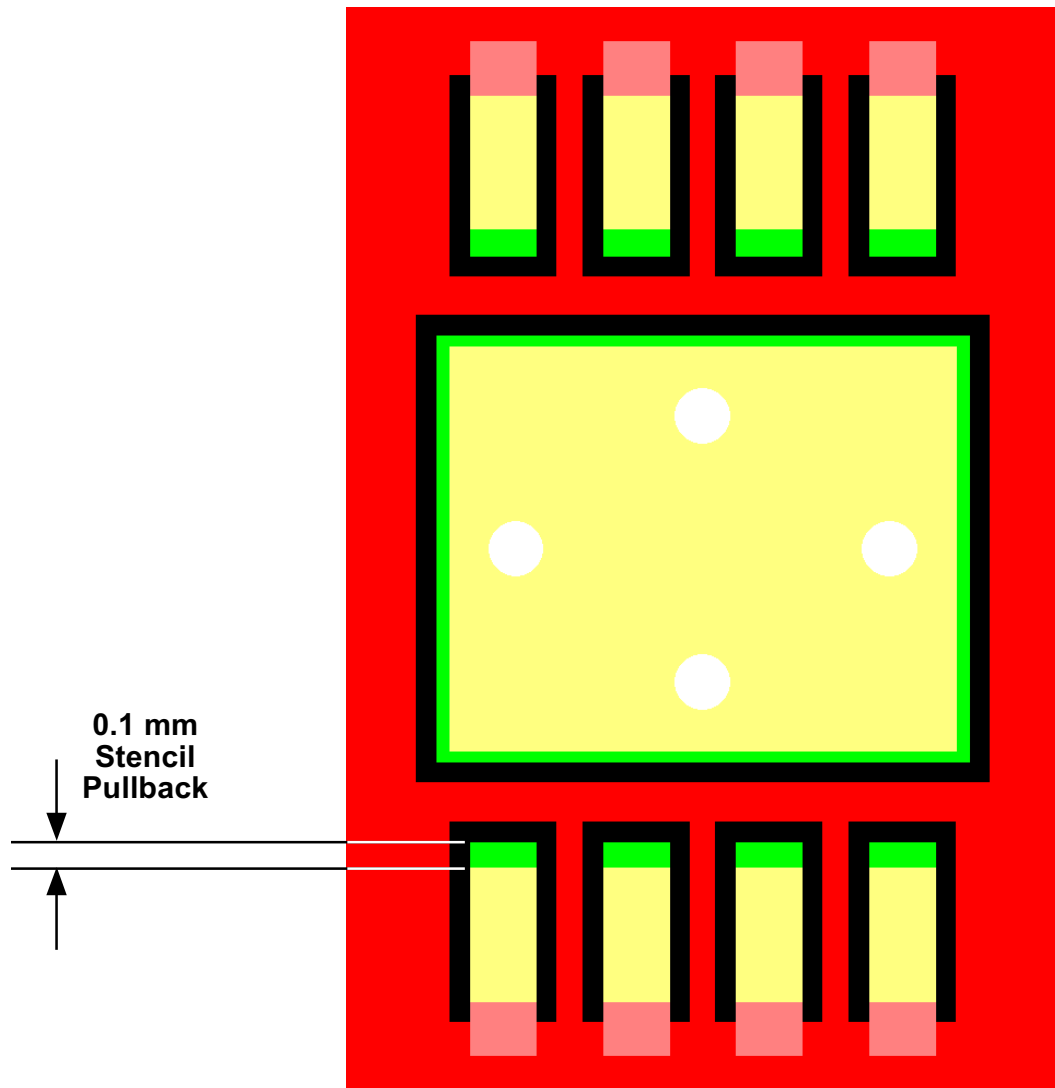
Note:
Recommended stencil thickness is
of 0.127mm (0.005").



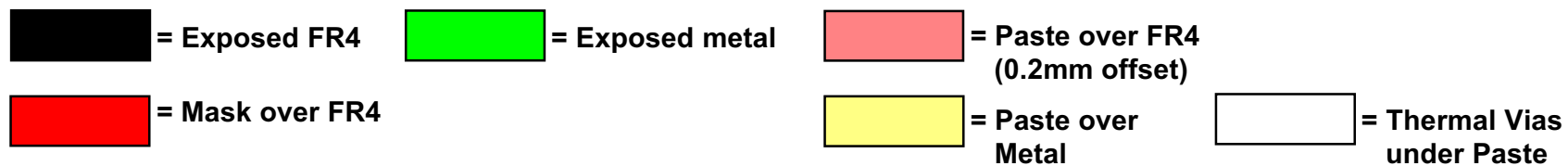
TOP SOLDERPASTE for Low Power Devices or PCBs with Inner Metal Ground Planes (Opt 2)

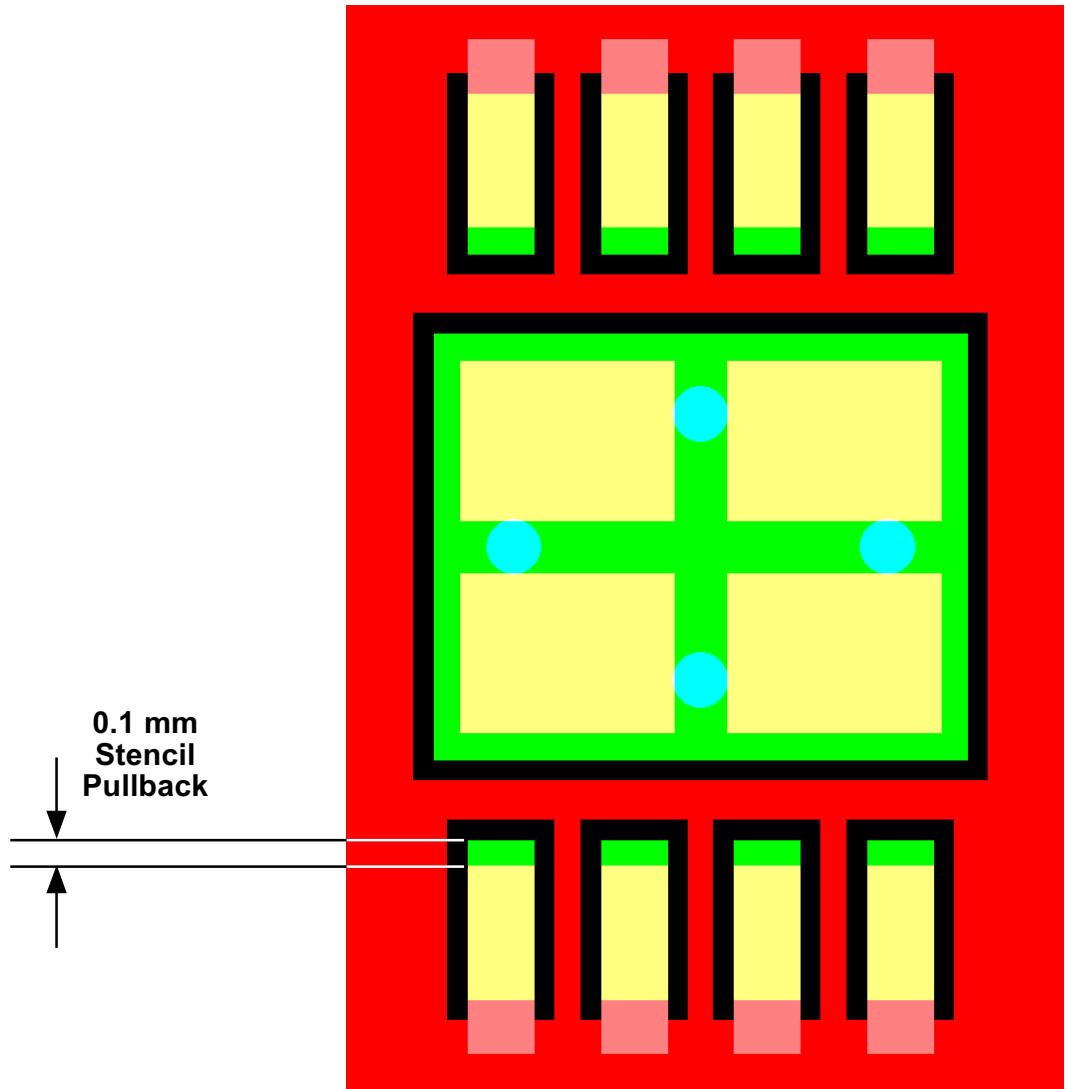
 = Paste

Note:
Recommended stencil thickness is of 0.127mm (0.005").

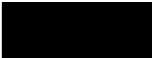




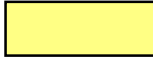


TOP ETCH + SOLDERMASK + SOLDERPASTE + VIAS (Opt 1)





TOP ETCH + SOLDERMASK + SOLDERPASTE + VIAS (Opt 2)

-  = Exposed FR4
-  = Exposed metal
-  = Paste over FR4 (0.2mm offset)
-  = Thermal Vias
-  = Mask over FR4
-  = Paste over Metal